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PRESS RELEASE

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Inseto's Geographical Remit Extends: Now Supplying Wafer Dicing Blades in Austria, Germany, Ireland, the Netherlands, Portugal and the UK.

Andover, United Kingdom – [Inseto](#), a leading technical distributor of equipment and materials, has been appointed Kulicke & Soffa's exclusive distributor for high-quality hubbed dicing blades in Austria, Germany, the Netherlands and Portugal. This appointment extends Inseto's geographical remit as the company has been supplying K&S dicing blades – as well as wire and wedge bonders, dispensing equipment and die bonders - in the UK and Ireland since 2008.

Hubbed dicing blades are used for cutting semiconductor wafers into individual die and are available with various grit sizes, diamond concentrations and binder hardnesses.

"We're delighted to have been appointed to distribute K&S's high quality hubbed dicing blades in Austria, Germany, the Netherlands and Portugal," comments Matt Brown, Director of Inseto. "These are countries in which our technical specialists are already well known and supporting customers active in semiconductor manufacturing."

Inseto has been supporting companies in the UK and Ireland with dicing blades for 16 years and is well versed in all technical aspects of wafer dicing. For example, silicon is a relatively soft material and single pass cuts are possible in most cases whereas as compound semiconductors, such as silicon carbide and gallium nitride, are harder and more brittle, often requiring multiple cuts to minimise the risk of sidewall cracking and chipping.

Brown adds: “Cut quality is governed by the size of the diamonds in the blade, the rate at which the binder material releases them - i.e. blade wear – the RPM at which the blade is spun and the rate at which it is moved through the wafer. Cooling and the use of surfactants also have an effect on cut quality, so there are lots of permutations to consider, and having gone to the expense of fabricating wafers it is important not to damage any die during the dicing process.”

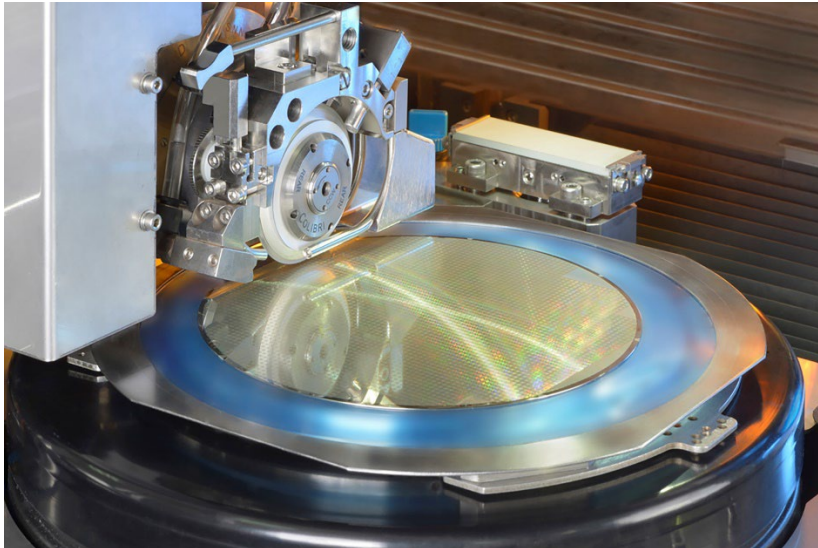
As a supplier of dicing saws and a variety of processing equipment, Inseto can also advise customers early on in their projects on issues such as optimum ‘street’ widths between die, as there is understandably a trade-off between getting as many die as possible on a wafer and being able to cut between them without causing damage. Inseto is also a supplier of semiconductor wafers and has a dedicated [online store](#).

“Our appointment by K&S to distribute hubbed blades in four more countries in Europe is great news in itself,” concludes Brown, “but it’s also broader recognition that Inseto has in-house expertise in all aspects of semiconductor manufacturing and that we’re able to help customers achieve a great economy of scale and return on investment.”

MAIN ENDS



Kulicke & Soffa’s exclusive distributor for hubbed dicing blades in the UK and Ireland since 2008, Inseto’s remit has been extended to include Austria, Germany, the Netherlands and Portugal.



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Notes to Editors

This press release was issued on behalf of Inseto (UK) Limited by technical content creation and communications agency DECLARATION (www.declaration.co.uk, +44 (0)1522 789000).

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About Inseto (UK) Limited

Established in 1987 and ISO 9001:2015 Certified since 2005, Inseto is a leading technical distributor of equipment and related materials to the semiconductor, microelectronic & advanced technology sectors, as well as adhesives for electronics, automotive and industrial manufacturing.

The company has three divisions, namely:

- **Equipment Division**, which provides manufacturing equipment for the Microelectronic, Photonic, Electronic, Photovoltaic and Semiconductor industries etc.
- **Consumable Division**, which provides assembly materials and machine consumable items for the Semiconductor, Electronic, Microelectronic, Photonic MEMS and Hybrid assembly industries etc.
- **Adhesive Division**, which provides technically advanced adhesives for bonding, sealing and encapsulation, and which exclusively represents DELO Industrial Adhesives in the UK and Ireland.

Inseto is based in Andover in a high-tech building that houses an adhesives application laboratory, demonstration areas for equipment and instrumentation, and training rooms.

Customer support is at the heart of Inseto's *Total Customer Service* philosophy, where the company aims to understand, communicate and fulfil the needs of its customers. The company is committed to meeting customer requirements through the application of high standards of quality and customer care (both before and after sales) by continually investing in training and adopting a policy of continuous improvement.

For further information please visit www.inseto.co.uk

About Kulicke & Soffa

Founded in 1951, Kulicke & Soffa specializes in developing cutting-edge semiconductor and electronics assembly solutions enabling a smart and more sustainable future. Our ever-growing range of products and services supports growth and facilitates technology transitions across large-scale markets, such as advanced display, automotive, communications, compute, consumer, data storage, energy storage and industrial.

For further information please visit www.kns.com